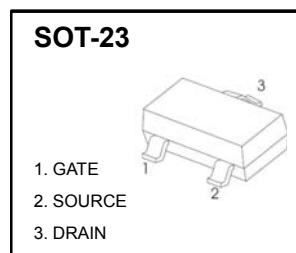


PAM2302 N-Channel 20-V(D-S) MOSFET

V(BR)DSS	Rds(on)MAX	ID
20V	60mΩ@4.5V	2.1A
	115mΩ@2.5V	



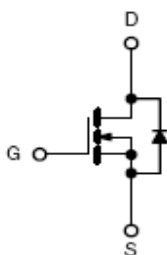
Features

- ◆ TrenchFET Power MOSFET

Applications

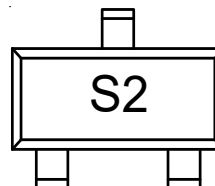
- ◆ Load Switch for Portable Devices
- ◆ DC/DC Converter

Dimensions and Pin Configuration



Circuit and Pin Schematic

Marking Information



Device Marking Code: S2

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±8	
Continuous Drain Current	I _D	2.1	A
Continuous Source-Drain Current(Diode Conduction)	I _S	0.6	
Power Dissipation	P _D	0.4	W
Thermal Resistance from Junction to Ambient (t≤5s)	R _{θJA}	312.5	°C/W
Operating Junction	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~+150	

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

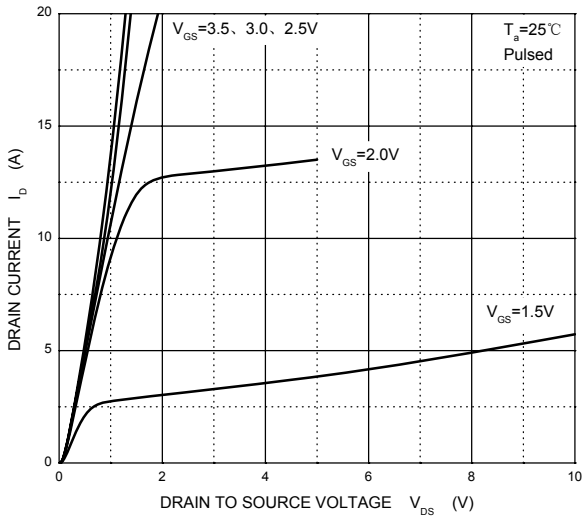
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 10\mu A$	20			V
Gate-threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 50\mu A$	0.65	0.95	1.2	
Gate-body leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			1	μA
Drain-source on-resistance ^a	$r_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3.6A$		0.035	0.060	Ω
		$V_{GS} = 2.5V, I_D = 3.1A$		0.045	0.115	
Forward transconductance ^a	g_{fs}	$V_{DS} = 5V, I_D = 3.6A$		8		S
Diode forward voltage	V_{SD}	$I_S = 0.94A, V_{GS} = 0V$		0.76	1.2	V
Dynamic						
Total gate charge	Q_g	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.6A$		4.0	10	nC
Gate-source charge	Q_{gs}			0.65		
Gate-drain charge	Q_{gd}			1.5		
Input capacitance ^b	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		300		pF
Output capacitance ^b	C_{oss}			120		
Reverse transfer capacitance ^b	C_{rss}			80		
Switching^b						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 10V,$ $R_L = 5.5\Omega, I_D \approx 3.6A,$ $V_{GEN} = 4.5V, R_g = 6\Omega$		7	15	ns
Rise time	t_r			55	80	
Turn-off delay time	$t_{d(off)}$			16	60	
Fall time	t_f			10	25	

Notes :

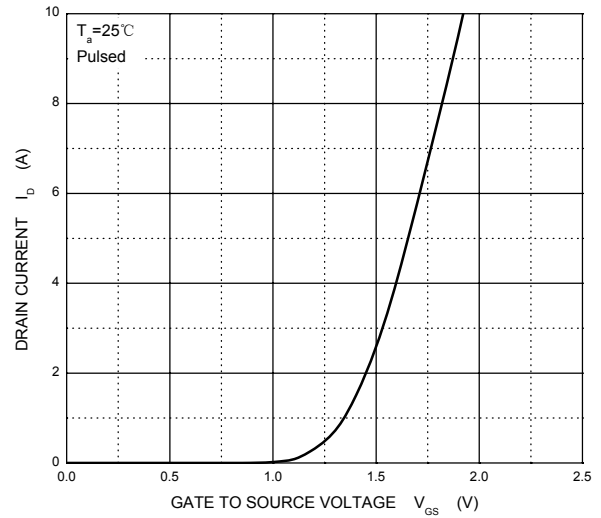
- Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- These parameters have no way to verify.

Typical Performance Characteristics (TA=25°C unless otherwise Specified)

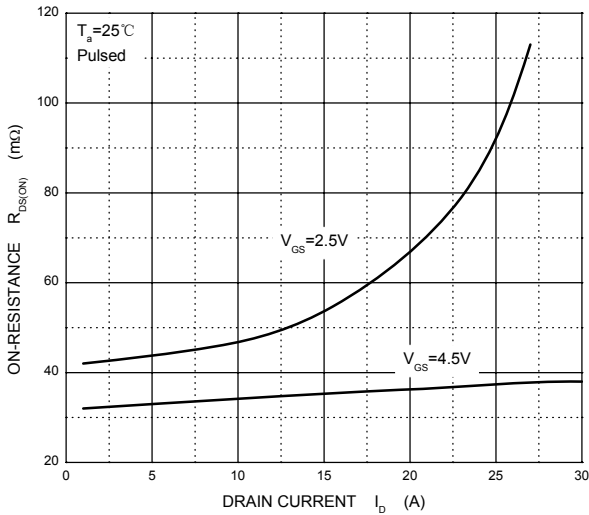
Output Characteristics



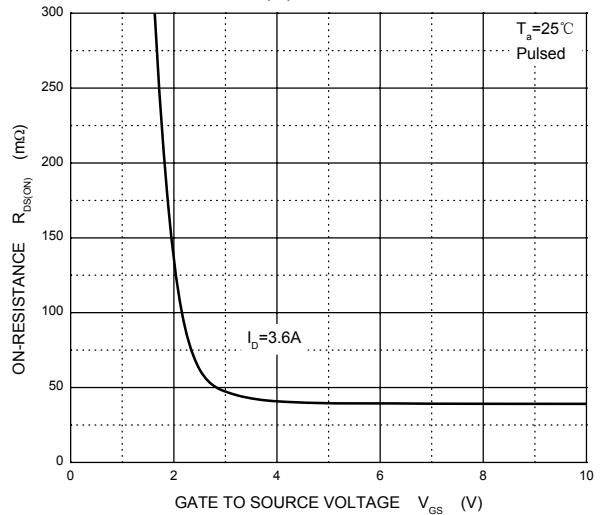
Transfer Characteristics



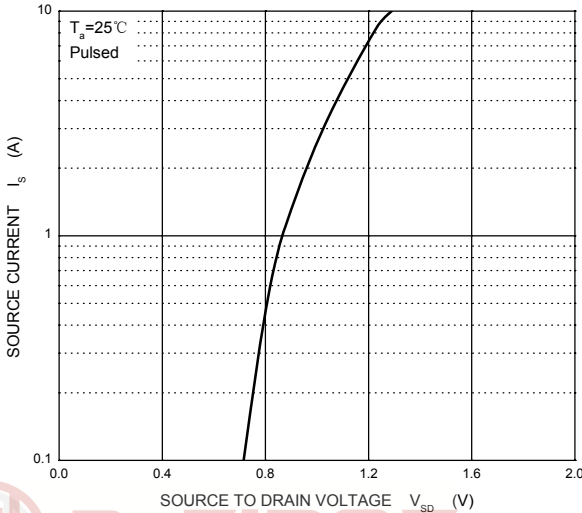
$R_{DS(ON)}$ — I_D



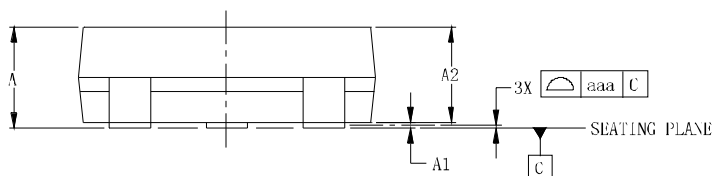
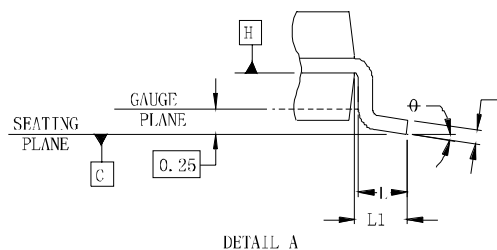
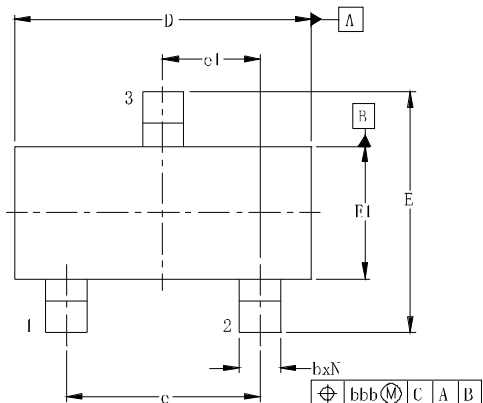
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}

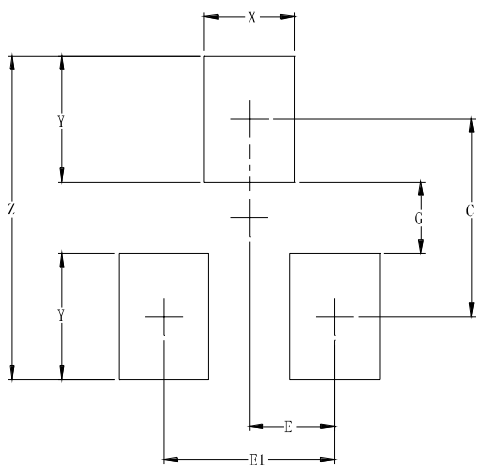


SOT-23 Package Outline Drawing



DIMENSIONS						
SYM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.035	-	0.044	0.89	-	1.12
A1	0.000	-	0.004	0.01	-	0.10
A2	0.035	0.037	0.040	0.88	0.95	1.02
b	0.012	-	0.020	0.30	-	0.51
c	0.003	-	0.007	0.08	-	0.18
D	0.110	0.114	0.120	2.80	2.90	3.04
E	0.082	0.093	0.104	2.10	2.37	2.64
E1	0.047	0.051	0.055	1.20	1.30	1.40
e	0.075			1.90BSC		
e1	0.037			0.95BSC		
L	0.015	0.020	0.024	0.40	0.50	0.60
L1	0.022			0.55		
N	3			3		
ϕ	0°	-	8°	0°	-	8°
aaa	0.004			0.10		
bbb	0.008			0.20		

Suggested Land Pattern



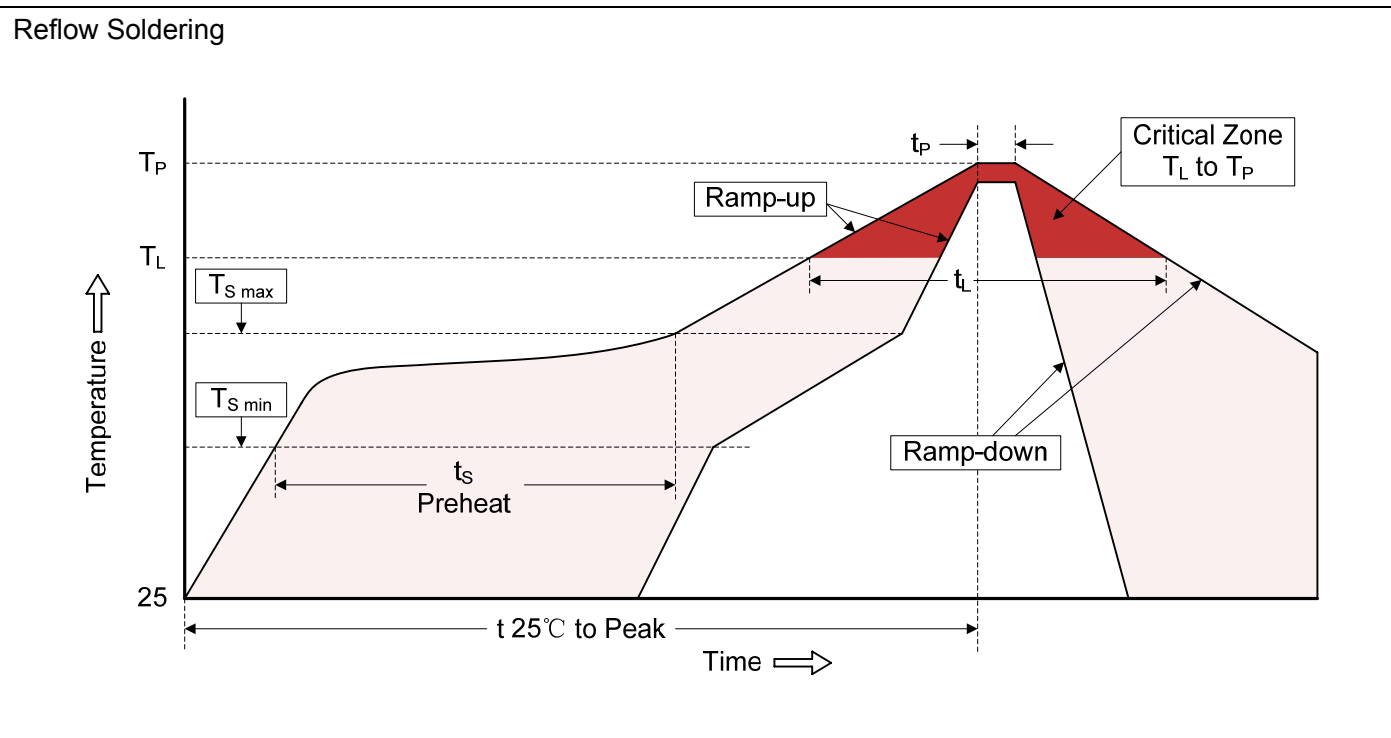
DIMENSIONS		
SYM	INCHES	MILLIMETERS
C	0.087	2.20
E	0.037	0.95
E1	0.075	1.90
G	0.031	0.80
X	0.039	1.00
Y	0.055	1.40
Z	0.141	3.60

Contact Information

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Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.